

# IEEE Wireless and Microwave Technology Conference

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Steven Lardizabal – Raytheon  
[slardiz03@ieee.org](mailto:slardiz03@ieee.org)

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Gokhan Mumcu – University of South Florida  
[mumcu@usf.edu](mailto:mumcu@usf.edu)

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Arya Menon – Texas A&M University  
[aryamenon@tamu.edu](mailto:aryamenon@tamu.edu)  
Michael Grady – GTRI  
[michael.grady@gtri.gatech.edu](mailto:michael.grady@gtri.gatech.edu)

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Eduardo Rojas – Embry-Riddle (East Coast) Aeronautical University  
[rojase1@erau.edu](mailto:rojase1@erau.edu)  
Advisor - Larry Dunleavy – Modelithics  
[ldunleavy@modelithics.com](mailto:ldunleavy@modelithics.com)

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Stavros Vakalis – University of South Florida  
[vakalis@usf.edu](mailto:vakalis@usf.edu)

## Paper Competition Chair

Jay McDaniel U of Oklahoma  
[jmcdaniel@ou.edu](mailto:jmcdaniel@ou.edu)

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Jim Culver - Raytheon  
[jwculver@ieee.org](mailto:jwculver@ieee.org)  
Serita Cronin – Tampa Microwave  
[s.cronin@tampamicrowave.com](mailto:s.cronin@tampamicrowave.com)

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Jim Assurian – Reactel  
[jassurian@reactel.com](mailto:jassurian@reactel.com)  
Laura Levesque – Modelithics  
[llevesque@modelithics.com](mailto:llevesque@modelithics.com)

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[mhallman@mwjournal.com](mailto:mhallman@mwjournal.com)  
Ryan Baker - Wolfsped, A Cree Company  
[ryan\\_baker@wolfsped.com](mailto:ryan_baker@wolfsped.com)

## Publications Chair

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[cdemartino@modelithics.com](mailto:cdemartino@modelithics.com)

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[craig\\_sapashe@keysight.com](mailto:craig_sapashe@keysight.com)

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[sbojjava@fiu.edu](mailto:sbojjava@fiu.edu)

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[Tom.weller@usf.edu](mailto:Tom.weller@usf.edu)

## IEEE YP Liaison

Daniel Ramirez– Harris  
[dramir02@harris.com](mailto:dramir02@harris.com)

## Women in Microwaves Chair

Maria Cordoba – Qorvo  
[maria15@mail.usf.edu](mailto:maria15@mail.usf.edu)

## Webmaster

Aditya Dave – University of Minnesota  
[davex033@umn.edu](mailto:davex033@umn.edu)

## WAMICON EXCOM Chair

Craig Sapashe – Keysight  
[craig\\_sapashe@keysight.com](mailto:craig_sapashe@keysight.com)



WAMICON 2023

April 17<sup>th</sup> and 18<sup>th</sup> 2023

Crowne Plaza Hotel  
Melbourne Beach, Florida

## Extended Deadline: Tuesday February 27, 2023

The 22<sup>nd</sup> annual IEEE Wireless and Microwave Technology Conference (WAMICON 2023) plans an engaging program in Melbourne, Florida on April 17<sup>th</sup> and 18<sup>th</sup> 2023. WAMICON 2023 addresses up-to-date RF and Microwave multidisciplinary research and technology trends from the latest on RF Power Amplifiers to AI concepts for RF and Systems. The program includes both oral and poster presentations as well as tutorials and special sessions. Melbourne provides a convenient location to the Orlando International airport and the East Coast of Florida. We invite prospective authors to submit original and high-quality work for presentation at WAMICON 2023 and publication in IEEE Xplore. Conference website is [www.wamicon.org](http://www.wamicon.org)

### TOPICS OF INTEREST INCLUDE

WAMICON 2023 Highlighting “Microwave and RF Innovations connecting Government, University and Business communities”. We welcome submissions on all aspects of RF Design and Microwave Microelectronics and Systems.

#### Power Amplifiers, Other Active Components, and Systems

High-Efficiency & Novel PAs, Linearization and Efficiency Enhancement Techniques, High-Power Devices, Linear/Nonlinear Device Modeling, Transceiver Design, Multi-Band and Digital RF Circuits and Systems, System-On-Chip/Package, Radar RF/MMIC Electronics, Active Filters, Reliability/Thermal Considerations, Wide Bandgap Semiconductors and Epitaxial Material Impacts.

#### Passive Components and Antennas

Filters, Transmission Line Components, Advanced Packaging, Antennas and Arrays, Meta-Materials, Frequency Selective Surfaces, Non-Foster Impedance Matching, Rectifiers

#### mm-Wave to THz Technologies

5G Communications, Backhaul, MIMO and Massive MIMO, Beamforming, Human Body Scanners, Radar, SatCom, Vehicle-to-Everything (V2x), Home/Office Application, Tactical Networks/Data Links, mm-wave Packaging, MEMS, and Integrated Circuits.

#### Space & Emerging Applications

CubeSats, SmallSats, FlatSats, Remote Sensors, Internet of Space, ASICS & Digital Back Ends, Optical Communications, Machine Learning, Spaceflight Qualification of Wireless Devices and Systems, Biomedical, Energy Harvesting, Wireless Power Transfer, Additive Manufacturing, Aerospace Applications of RF Circuits and System, Space Vehicle Com.

#### Internet of Everything (IoE)

Automotive Systems, Health and Medical Sensors, Machine-to-Machine (M2M), Bluetooth Low Energy (BLE), Light Fidelity (Li-Fi), Near-Field Communication (NFC), RFID, Zigbee, Low-Power Wide-Area Network (LPWAN), Active Denial, Cognitive Radios and Software Defined Radios, Spectrum Management, Wireless Security, AI for RF and Systems.

### PAPER SUBMISSION INSTRUCTIONS

Authors are asked to submit papers electronically in .PDF format. In order to be considered for publication by the Technical Program Committee, a submission of 3-4 pages, clearly describing the concept and results must be submitted before the deadline of February 8, 2023. The conference webpage at [www.wamicon.org](http://www.wamicon.org) has complete details of submission requirements. Submissions will be evaluated for originality, significance of the work, technical soundness, and interest to a wide audience.



Extended Paper Date: Tue., Feb. 27, 2023  
Author Notification: Mon., Mar. 13, 2023  
Final Papers Due: Mon., Mar. 21, 2023